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(54) **ELECTRONIC PACKAGE AND SUBSTRATE STRUCTURE THEREOF**

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(57) **ABSTRACT**

An electronic package is provided, which includes a substrate structure and an electronic element and a passive element disposed on the substrate structure, where a die placement area and a functional area separated from each other are defined on a surface of a substrate body of the substrate structure, so that a routing layer is arranged with linear conductive traces with a smaller width in the die placement area, and a sheet-shaped circuit with a larger width and electrically connected to the linear conductive traces is arranged in the functional area, so as to reduce a metal area on the surface of the substrate body, thereby avoiding the problem of warpage caused by stress concentration in the die placement area.

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